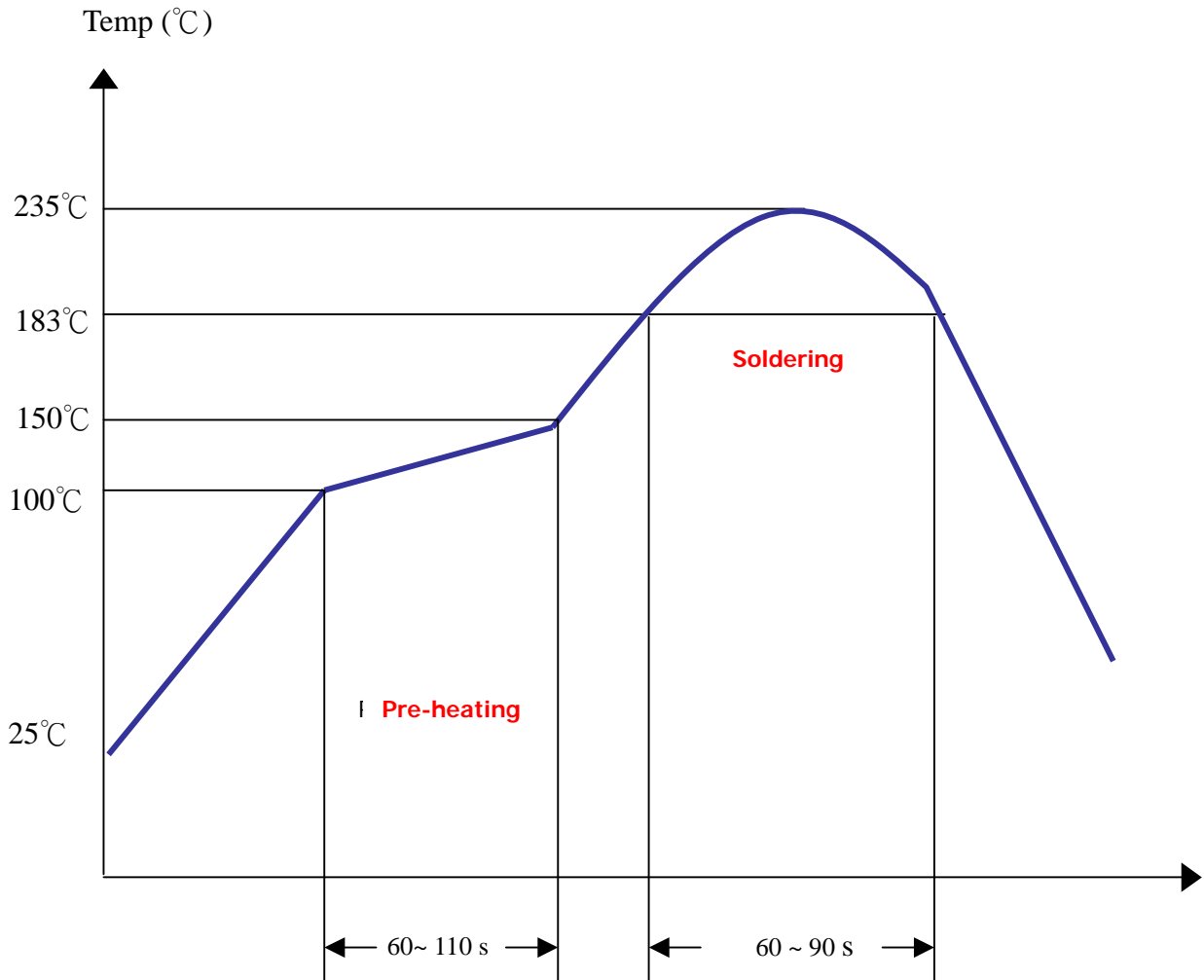


Reflow Profiles for ICs with Sn-Pb eutectic assembly

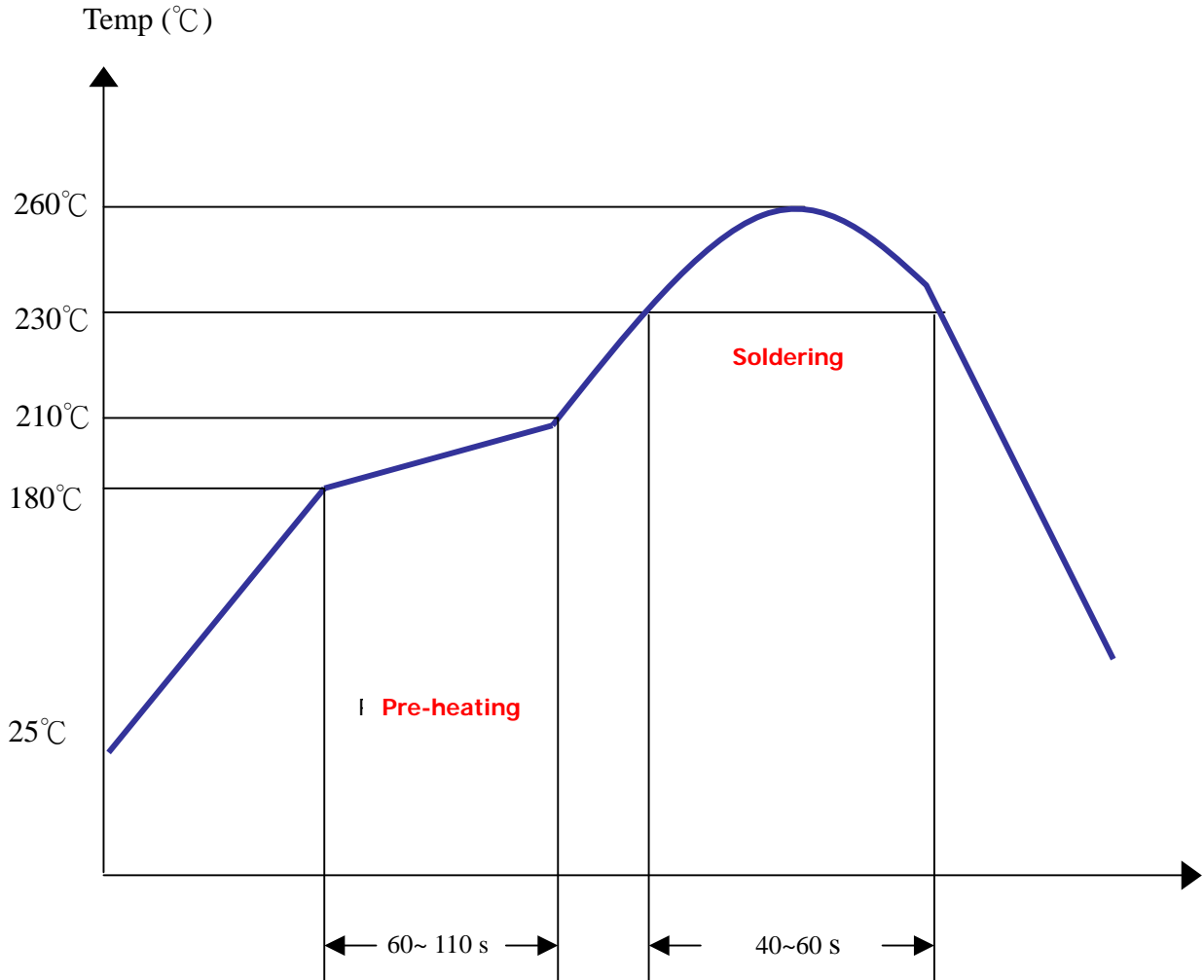


Testing Content:

<u>STAGE</u>	<u>CONDITION</u>	<u>DURATION</u>
1'st Ram Up	3.0+/-2°C/sec	
Preheat	100°C~150°C	60~110 secs
2'nd Ram Up	2.0+/-1°C/sec	
Solder Joint	183°C above	60~90 secs
Peak Temp	235+5/-0°C	5 secs
Rpmp Down rate	-6°C/sec max	



SMT Reflow Profiles for ICs with Pb-Free assembly



Testing Contents:

<u>STAGE</u>	<u>CONDITION</u>	<u>DURATION</u>
1'st Ram Up	3.0+/-2°C/sec	
Preheat	180°C~210°C	60~110 secs
2'nd Ram Up	2.0+/-1°C/sec	
Solder Joint	230°C above	40~60 secs
Peak Temp	260+5/-0°C	5 secs
Rpmp Down rate	-6°C/sec max	

Classification of Pb-Free products

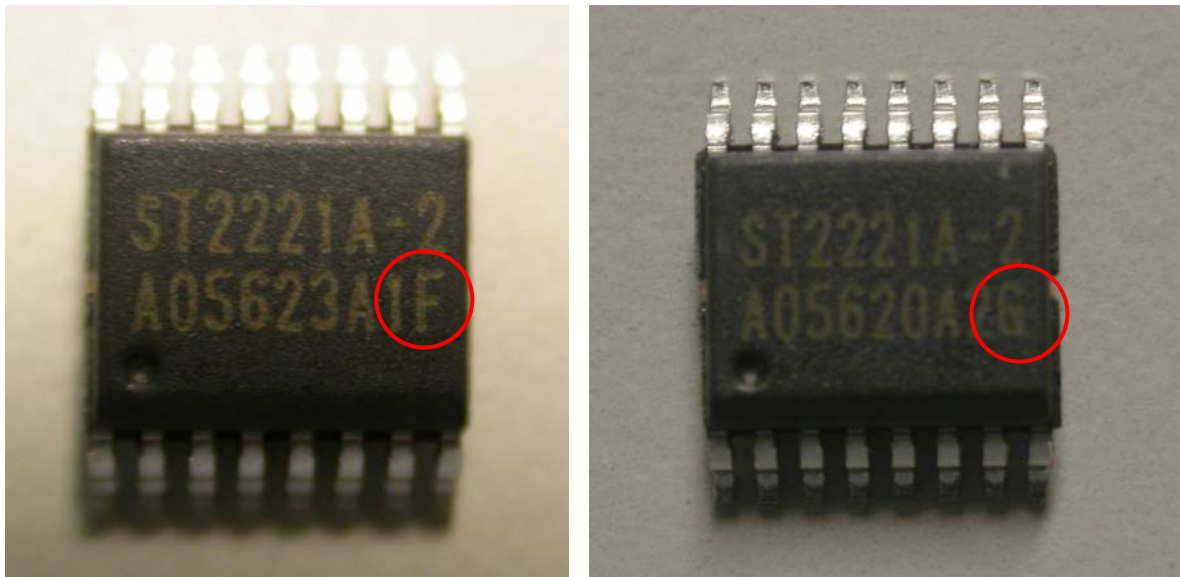
There are two ways could be adopted to identify whether received ICs were manufactured with Pb-Free assembly or not.

First, the “Pb-Free” or “Green Pb-Free” marking could be sufficiently observed within the labels on outer box and tapes containing the ICs. The label type is shown as Figure1.

PRODUCT	: ST2221A-2(Pb-Free)	PRODUCT	: ST2221A-2(Green Pb-Free)
PACKAGE	: SSOP16	PACKAGE	: SSOP16
QUANTITY	: 2500	QUANTITY	: 2500 PCS
DATE CODE	: A05623A1F	DATE CODE	: A05620A2G (#2)

(Figure 1)

Second, an additional letter “F” (or “G” for green compound used) will be marked following the end of datecode on each IC’s surface. Please see the figure2.



(Figure 2)